

Document Number	Hits	Search Text	DB	Time stamp
-	133	((integrat\$3 chip\$1) near3 induct\$3) not (((chip same induct\$3) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1) near10 (pad\$1 bump\$1)))) and ((integrat\$3 chip\$1) near3 induct\$3) and (pad\$1 bump\$1 ubm solder)) and ((hole\$1 via\$1 opening\$1 aperture\$1 recess\$3 groove\$1 trench\$2) near10 (pad\$1 bump\$1 ubm solder))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 12:58
-	4133	(integrat\$3 chip\$1) near3 (induct\$3 coil\$1 wire\$1 transformer\$1) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1 recess\$3 cavit\$3) near10 (pad\$1 bump\$1 solder\$1))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 13:06
-	424	((integrat\$3 chip\$1) near3 (induct\$3 coil\$1 wire\$1 transformer\$1) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1 recess\$3 cavit\$3) near10 (pad\$1 bump\$1 solder\$1))) and (thick\$4 near7 (induct\$3 coil\$1 wire\$1 transformer\$1))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 13:21
-	31	((integrat\$3 chip\$1) near3 (induct\$3 coil\$1 wire\$1 transformer\$1) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1 recess\$3 cavit\$3) near10 (pad\$1 bump\$1 solder\$1))) and (thick\$4 near7 (induct\$3 coil\$1 wire\$1 transformer\$1)) and (integrat\$3 adj (induct\$3 coil\$1 wire\$1 transformer\$1))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 13:16
-	5	((integrat\$3 chip\$1) near3 (induct\$3 coil\$1 wire\$1 transformer\$1) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1 recess\$3 cavit\$3) near10 (pad\$1 bump\$1 solder\$1))) and (thick\$4 near7 (induct\$3 coil\$1 wire\$1 transformer\$1)) and ("on-chip" adj (induct\$3 coil\$1 wire\$1 transformer\$1))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 13:16
-	424	((integrat\$3 chip\$1) near3 (induct\$3 coil\$1 wire\$1 transformer\$1) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1 recess\$3 cavit\$3) near10 (pad\$1 bump\$1 solder\$1))) and (thick\$4 near7 (induct\$3 coil\$1 wire\$1 transformer\$1)) and (thick\$4 near7 (induct\$3 coil\$1 wire\$1 transformer\$1))	USPAT; US-PGPUB; EPO; JPO	2002/09/27 13:21

L Number	Hits	Search Text	DB	Time stamp
1	501	((chip same induct\$3) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1) near10 (pad\$1 bump\$1)))	USPAT; US-PPGPUB; EPO; JPO	2002/09/20 13:40
6	3285	((integrat\$3 chip\$1) near3 induct\$3) not (((chip same induct\$3) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1) near10 (pad\$1 bump\$1))))	USPAT; US-PPGPUB; EPO; JPO	2002/09/20 13:40
11	702	((((integrat\$3 chip\$1) near3 induct\$3) not (((chip same induct\$3) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1) near10 (pad\$1 bump\$1))))) and ((integrat\$3 chip\$1) near3 induct\$3) and (pad\$1 bump\$1 ubm solder))	USPAT; US-PPGPUB; EPO; JPO	2002/09/20 13:43
16	133	(((((integrat\$3 chip\$1) near3 induct\$3) not (((chip same induct\$3) and ((hole\$1 opening\$1 trench\$2 groove\$1 aperture\$1 via\$1) near10 (pad\$1 bump\$1))))) and ((integrat\$3 chip\$1) near3 induct\$3) and (pad\$1 bump\$1 ubm solder)) and ((hole\$1 via\$1 opening\$1 aperture\$1 recess\$3 groove\$1 trench\$2) near10 (pad\$1 bump\$1 ubm solder))	USPAT; US-PPGPUB; EPO; JPO	2002/09/20 13:45